

REMARKS

Introduction

With this amendment, the two previously pending independent claims 1 and 11 have been amended, the depending claims have been amended to make them consistent with the amended independent claims, claim 5 has been canceled, and new claims 13 to 25 have been added. Claims 1-4 and 6-25 are pending. Claims 1, 11 and 15 are the pending independent claims.

The Problems Solved By Applicants

Applicant has provided a smart label with capacitor having a high quality factor where the smart label can be made with high speed manufacturing and accurately connect a chip through a capacitor to a circuitry pattern on a smart label substrate. The advantages of the Applicant's smart label include those set forth on pages 3-4 of the specification. Applicant contemplates a chip which includes an integrated circuit to be placed more accurately than what is shown in the prior art. The chip is part of a structural part applied to the smart label substrate, and the structural part is substantially smaller than a smart label substrate. This design permits a chip dispenser with short paths to perform accurate placement of the chip. Moreover, using a small structural part relative to the smart label substrate permits wider tolerances in the placement of the structural part on the smart label substrate. Finally, differing sizes of opposing capacitor plates also permit a variation tolerance and yet permit connection of the circuitry pattern with the integrated circuit on the chip.

The Art Rejection

The Examiner has rejected claims 1-3 and 9 as anticipated by Seiichi (JP 2000057287). The Examiner also rejected claims 10-12 as obvious over Seiichi. Seiichi does not describe or even remotely suggest the aspects of Applicant's smart label as discussed above. Seiichi does not disclose or remotely suggest a small structural part relative to a smart label substrate which has a circuitry pattern thereon. Moreover, Seiichi does not remotely suggest opposed capacitor plates

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of differing sizes to permit larger tolerances in placing the chip and connecting the chip to the circuitry pattern through one or more capacitors.

The Section 112 Rejections

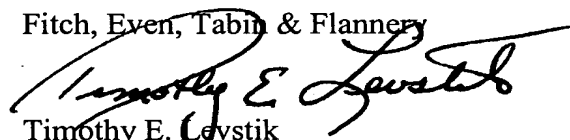
The Examiner rejected claims 4-9 under 35 USC §112. The Examiner questioned how an anisotropically conductive film could be a dielectric. It is not. Claim 5 which may have implied it is has been canceled. The thermoplastic film can be anisotropically conductive, but then it is isolated from the circuitry pattern. If the anisotropically conductive thermoplastic film is on the opposite side as the circuitry pattern, the smart label substrate serves as the dielectric. This is described at page 8, lines 10-15 of the specification. As to claim 4, something other than the anisotropic conductive film has to serve as the dielectric. The rejection of these claims should be obviated, and not being rejected on art, claims 4-9 should be passed to allowance.

Conclusion

Applicant respectfully submits that no reference alone or in combination anticipate or render the pending claims obvious. Further, the section 112 rejections have been obviated. In view of the foregoing, applicant respectfully requests reconsideration and allowance of the pending claims.

Respectfully submitted,

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